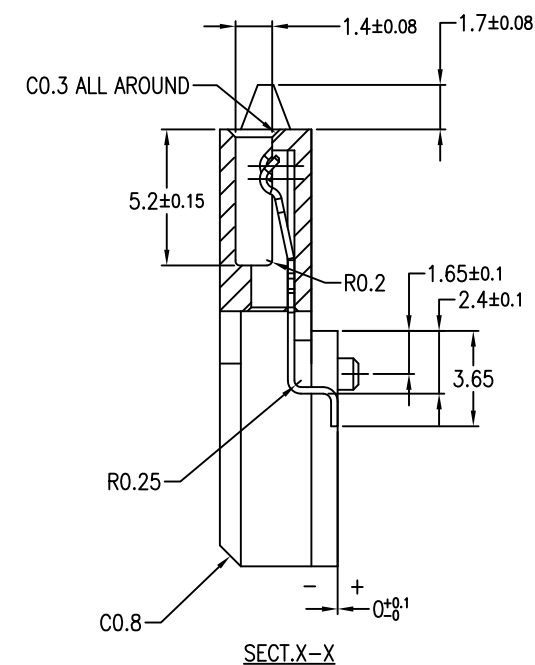
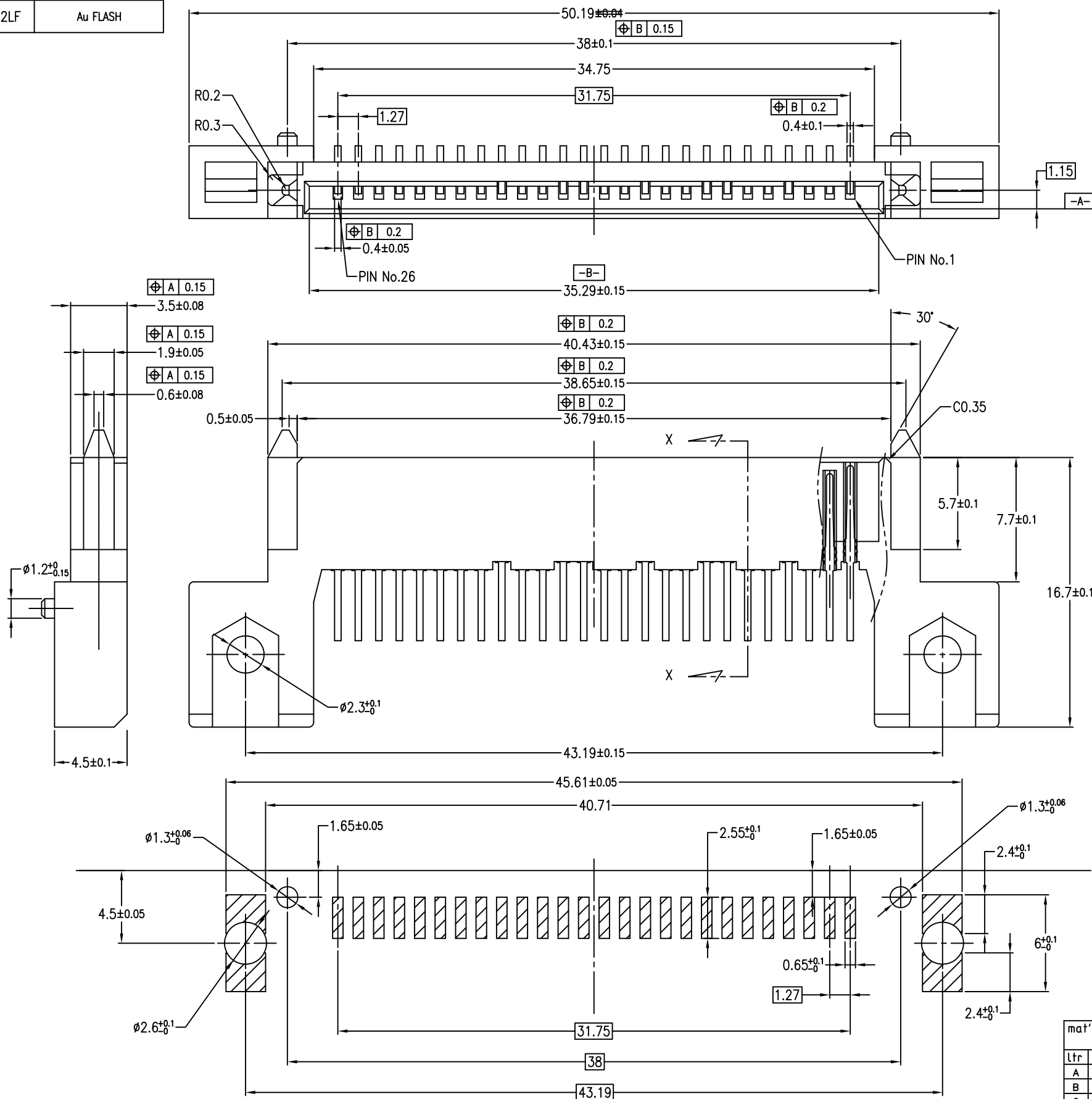


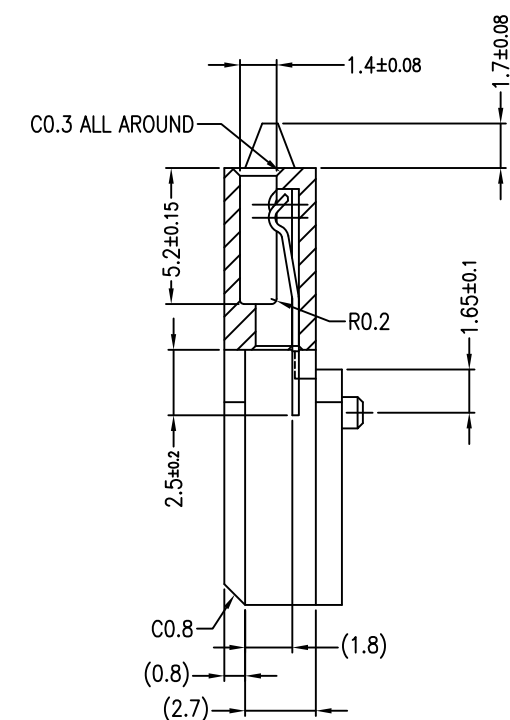
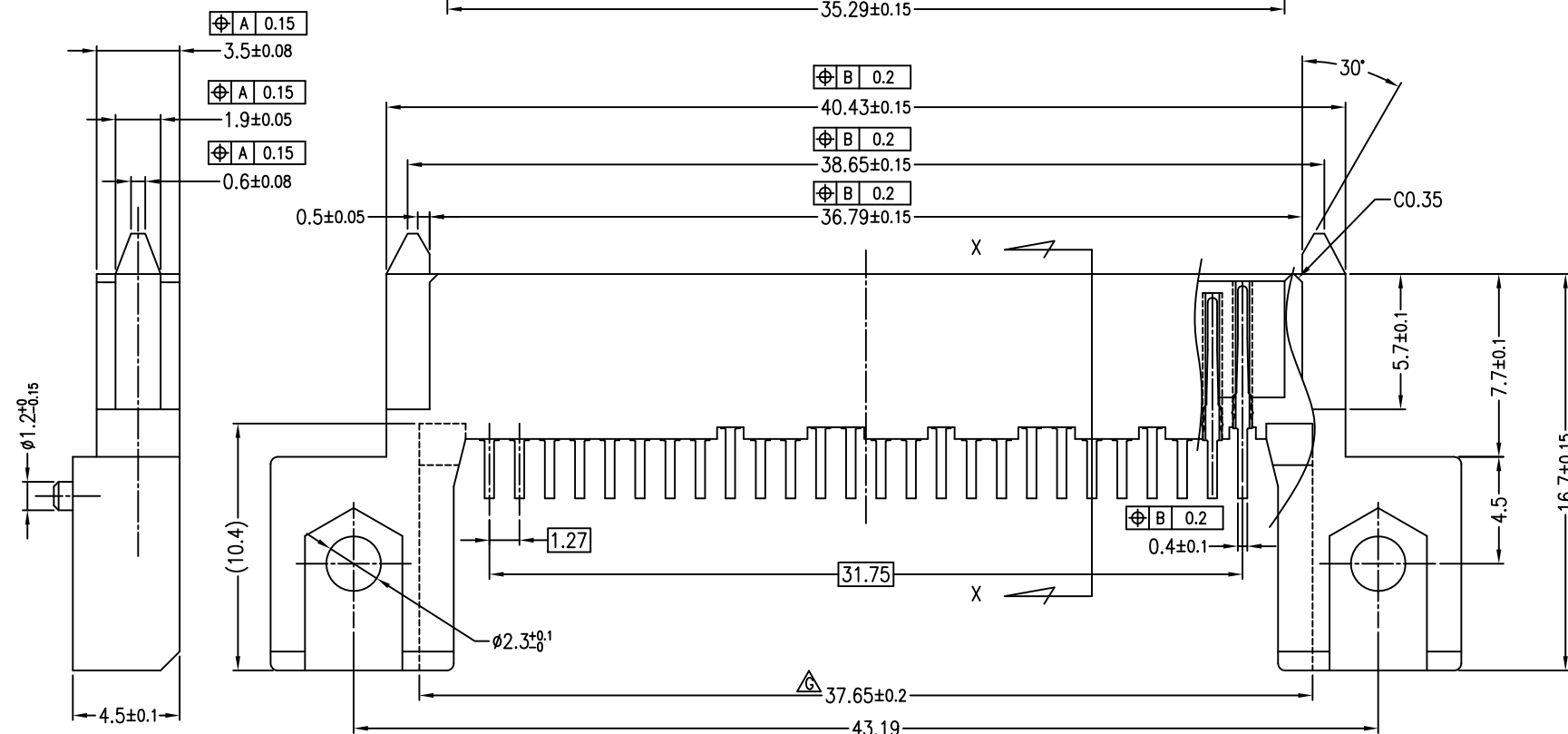
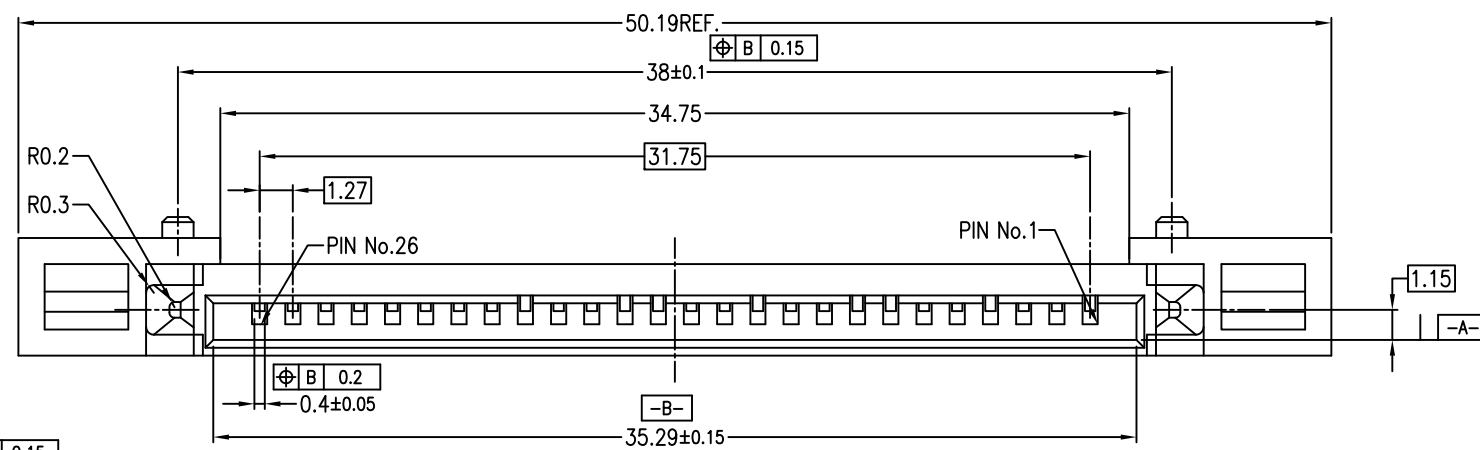
|                |                      |
|----------------|----------------------|
| PRODUCT NO.    | FINISH : Solder Tail |
| 10033998-001   | Pure Sn 1.27μm MIN.  |
| 10033998-002   | Au FLASH             |
| 10033998-002LF | Au FLASH             |



- NOTE
- THIS PRODUCT MEETS THE iVDR-HWSPEC (2.5-inch, 1.8-inch Serial type)
  - MATERIAL
    - HOUSING : HIGH TEMPERATURE THERMOPLASTIC,BLACK, UL94V-0
    - TERMINAL : COPPER ALLOY
  - FINISH
    - TERMINAL : ALL OVER Ni 1.27μm MIN.  
CONTACT POINT Au PLATING 0.3μm MIN.  
SOLDER TAIL SEE TABLE
  - RoHS  
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONSAS DESCRIBED IN GS-22-008

RECOMMENDED MOUNTING LAYOUT  
TOLERANCE UNLESS OTHERWISE:±0.1

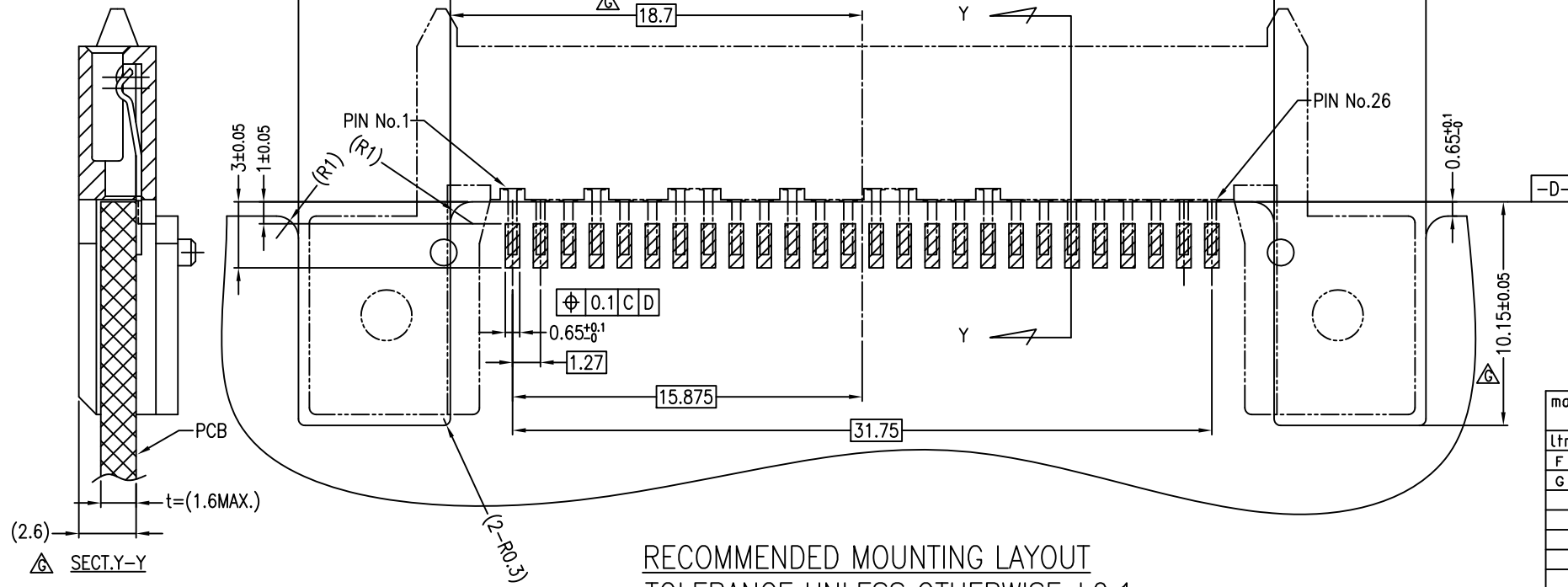
|                    |                   |             |     |                     |   |                  |                                  |                         |
|--------------------|-------------------|-------------|-----|---------------------|---|------------------|----------------------------------|-------------------------|
| mat'l. code<br>--- |                   |             |     | surface<br>ISO 1302 | tolerance<br>ISO 406<br>ISO 1101            | projection<br>MM | product family<br>53MF           | CODE<br>JP              |
| ltr                | description       | ecn no      | dr  | date                | tolerances<br>unless<br>otherwise specified | MM               | title                            |                         |
| A                  | RELEASED          | J04-0286    | Y.K | 8/23/'04            | 0.X ±0.3                                    |                  | ASSEMBLY                         |                         |
| B                  | REVISED           | J05-0107    | Y.K | 2/24/'05            | 0.XX ±0.3                                   |                  | S-iVDR COMB RECE.                |                         |
| C                  | Change DWG form   | J07-0041    | Y.K | 1/23/'07            | 0.XXX ±0.3                                  | scale 5:1        | SMT R/A TYPE                     |                         |
| D                  | Change of P/N     | J07-0464    | Y.K | 2007-9-13           | dr  | Y.KAMEDA         | 2014-05-16                       |                         |
| E                  | Change of P/N     | J08-0253    | Y.K | 2008-6-12           | enrg  | Y.KAMEDA         | 2014-05-16                       |                         |
| F                  | Add sheet2        | J09-0416    | Y.K | 2008-6-12           | chr   | M.MINATO         | 2014-05-16                       |                         |
| G                  | Change of sheet2  | ELX-J-17883 | Y.K | 2014-05-16          | appd  | N.SASAME         | 2014-05-16                       |                         |
| sheet<br>index     | revision<br>sheet | G           | G   | 1                   | 2   |                  | dwg no<br>10033998               | sheet 1 of 2 size<br>A2 |
|                    |                   |             |     |                     |   |                  | type<br>Product Customer Drawing | Rev.<br>G               |

SECT.X-X

NOTE

1. THIS PRODUCT MEETS THE IVDR-HWSPEC (2.5-inch, 1.8-inch Serial type)
2. MATERIAL
- 1) HOUSING : HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0
- 2) TERMINAL : COPPER ALLOY
3. FINISH
- 1) TERMINAL : ALL OVER Ni 1.27 $\mu$ m MIN.  
CONTACT POINT Au PLATING 0.3 $\mu$ m MIN.  
SOLDER TAIL Au Flash

4.RoHS  
THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER  
COUNTRY REGULATIONSAS DESCRIBED IN GS-22-008



RECOMMENDED MOUNTING LAYOUT  
TOLERANCE UNLESS OTHERWISE:  $\pm 0.1$

[illegible]